



## Material Content Data Sheet



<b>Sales Product Name</b>		BSO604NS2		<b>Issued</b>		25. September 2017		
<b>MA#</b>		MA000977786						
<b>Package</b>		PG-DSO-8-25		<b>Weight*</b>		83.62 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.327	3.98	3.98	39792	39792
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		107	
	non noble metal	zinc	7440-66-6	0.036	0.04		429	
	non noble metal	iron	7439-89-6	0.717	0.86		8577	
wire	non noble metal	copper	7440-50-8	29.121	34.83	35.74	348277	357390
	noble metal	gold	7440-57-5	0.417	0.50	0.50	4989	4989
	encapsulation	organic material	carbon black	1333-86-4	0.095	0.11		1134
plastics	plastics	epoxy resin	-	4.363	5.22		52177	
	inorganic material	silicondioxide	60676-86-0	42.964	51.38	56.71	513832	567143
leadfinish	non noble metal	tin	7440-31-5	0.814	0.97	0.97	9733	9733
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7777	7777
glue	plastics	epoxy resin	-	0.193	0.23		2306	
	noble metal	silver	7440-22-4	0.909	1.09	1.32	10870	13176
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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